

AMENDMENTS TO THE CLAIMS:

The present Amendment has been prepared in accordance with a revised format established by the U.S. Patent and Trademark Office, as permitted in the Pre-OG Notice entitled "Amendments in a Revised Format Now Permitted."

Please amend Claims 11, 14, 33, and 38 as follows. In accordance with the revised amendment format, all claims are presented below.

Sub
C/

1-7 (Cancelled)

8. (Previously Amended) The semiconductor device according to claim 33, wherein a power supply voltage of said correction circuit output chip is higher than a power supply voltage of said photo sensor chips.

B1
C/

9. (Cancelled)

10. (Cancelled)

11. (Currently Amended) The semiconductor device according to claim 33, wherein GND wiring for said correction circuit output chip and GND wiring for said photo sensor chips are isolated from each other on said single mounting substrate.

12. (Cancelled)

13. (Cancelled)

14. (Currently Amended) The semiconductor device according to claim 8, wherein GND wiring for said correction circuit output chip and GND wiring for said photo sensor chips are isolated from each other on said single mounting substrate.

15-32 (Cancelled)

33. (Currently Amended) An image sensor comprising:

B1
Cont

a plurality of photo sensor chips mounted on a single mounting substrate, each photo sensor chip having a plurality of photoelectric conversion circuits, a common output line through which signals from said plurality of photo-electric conversion circuits are outputted, and a photo sensor chip output device which outputs signals from said common output line to outside of said photo sensor chip; and

a correction circuit output chip mounted on said single mounting substrate, said correction circuit output chip having a noise compensation circuit which compensates for a noise component included in a photo-electric conversion signal read out from said photo sensor chip output device, by using a noise signal read out from said photo sensor chip output device,

wherein said correction circuit output chip is arranged commonly to said plurality of photo sensor chips, and ~~an output signal from said correction circuit output chip is outputted from said mounting substrate for use off of said mounting substrate~~

wherein an output terminal for outputting a signal to outside of said correction circuit output chip and an output terminal for outputting a signal to outside of said single mounting substrate are connected to each other.

34. (Previously Added) The image sensor according to claim 33, wherein said noise compensation circuit has a differential circuit which calculates a difference between a first signal and a second signal and a clamp circuit connected to an output of said differential circuit.

35. (Previously Added) The image sensor according to claim 34, wherein said differential circuit calculates a difference between the noise signal and the photo-electric conversion signal read out from said photo sensor chip output device and said clamp circuit clamps a reset state of said common output line in said photo sensor chip.

36. (Previously Added) The image sensor according to claim 33, wherein said noise compensation circuit has a plurality of clamp circuits that are serially connected.

37. (Previously Added) The image sensor according to claim 33, wherein said noise compensation circuit has a clamp circuit which clamps a reset state of said common output line in said photo sensor chip.

38. (Currently Amended) A method of driving an image sensor, said image sensor including:

(a) a plurality of photo sensor chips mounted on a single mounting substrate, each photo sensor chip having a plurality of photo-electric conversion circuits, a common output line through which signals from said plurality of photo-electric

conversion circuits are outputted, and a photo sensor chip output device which outputs signals from said common output line to outside of said photo sensor chip; and

(b) a correction circuit output chip mounted on said single mounting substrate, said correction circuit output chip having a noise compensation circuit,

wherein said correction circuit output chip is arranged commonly to said plurality of photo sensor chips, and ~~an output signal from said correction circuit output chip is outputted from said mounting substrate for use off of said mounting substrate~~

*B1
cancel*
wherein an output terminal for outputting a signal to outside of said correction circuit output chip and an output terminal for outputting a signal to outside of said single mounting substrate are connected to each other,

said method comprising the step of:

driving said compensation circuit to compensate for a noise component included in a photo-electric conversion signal read out from said photo sensor chip output device by using a noise signal read out from said photo sensor chip output device.
